

# “HALF-BRIDGE” IGBT MODULE

**V<sub>CES</sub> = 1200V**  
**I<sub>c</sub> = 75A**  
**V<sub>CE(ON)</sub> typ. = 2.6V**  
**@ I<sub>c</sub> = 75A**

## Features

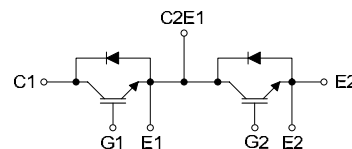
- Smarted NPT Technology Design
- 10μs Short circuit capability
- Low turn-off losses
- Short tail current for over 18KHZ
- Positive V<sub>CE(on)</sub> temperature coefficient

## Applications

- AC & DC Motor controls
- VVVF inverters
- Optimized for high frequency inverter Type Welding machines
- High frequency SMPS
- UPS, Robotics



**Package : V1**



## Absolute Maximum Ratings @ T<sub>c</sub> = 25 (per leg)

Symbol	Parameter	Condition	Ratings	Unit
V <sub>CES</sub>	Collector-to-Emitter Voltage	V <sub>GE</sub> = 0V, I <sub>c</sub> = 500μA	1200	V
V <sub>GES</sub>	Gate emitter voltage		± 20	V
I <sub>c</sub>	Continuous Collector Current	T <sub>c</sub> = 80	75	A
I <sub>CM</sub>	Pulsed collector current	T <sub>c</sub> = 80	150	A
I <sub>F</sub>	Diode Continuous Forward Current	T <sub>c</sub> = 80	75	A
I <sub>FM</sub>	Diode Maximum Forward Current		150	A
T <sub>SC</sub>	Short Circuit Withstand Time		10	μs
V <sub>iso</sub>	Isolation Voltage test	AC 1 minute	2500	V
T <sub>j</sub>	Junction Temperature		-40 ~ 150	
T <sub>stg</sub>	Storage Temperature		-40 ~ 125	
Weight	Weight of Module		190	g
Mounting	Power Terminal Screw : M5		3.5	Nm
Torque	Terminal connection Screw : M5		3.5	Nm

## Electrical Characteristics @ T<sub>j</sub> = 25 (unless otherwise specified)

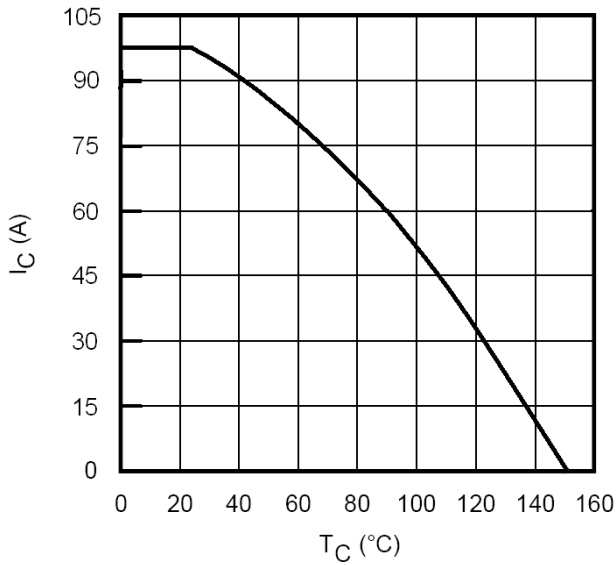
Symbol	Parameters	Min	Typ	Max	Unit	Test conditions
V <sub>(BR)CES</sub>	Collector-to-Emitter Breakdown Voltage	1200	-	-	V	V <sub>GE</sub> = 0V, I <sub>c</sub> = 500μA
V <sub>CE(ON)</sub>	Collector-to-Emitter Saturation Voltage	-	2.6	2.8		I <sub>c</sub> = 75A, V <sub>GE</sub> = 15V
V <sub>GE(th)</sub>	Gate Threshold Voltage	-	5.0	6.0		V <sub>CE</sub> = V <sub>GE</sub> , I <sub>c</sub> = 500μA
I <sub>CES</sub>	Zero Gate Voltage Collector Current	-	-	500	μA	V <sub>GE</sub> = 0V, V <sub>CE</sub> = 1200V
I <sub>GES</sub>	Gate-to-Emitter Leakage Current	-	-	± 100	nA	V <sub>CE</sub> = 0V, V <sub>GE</sub> = ± 20V
V <sub>FM</sub>	Diode Forward Voltage Drop	-	2.1	2.4	V	I <sub>c</sub> = 75A

**Switching Characteristic @  $T_j = 25$**  (unless otherwise specified)

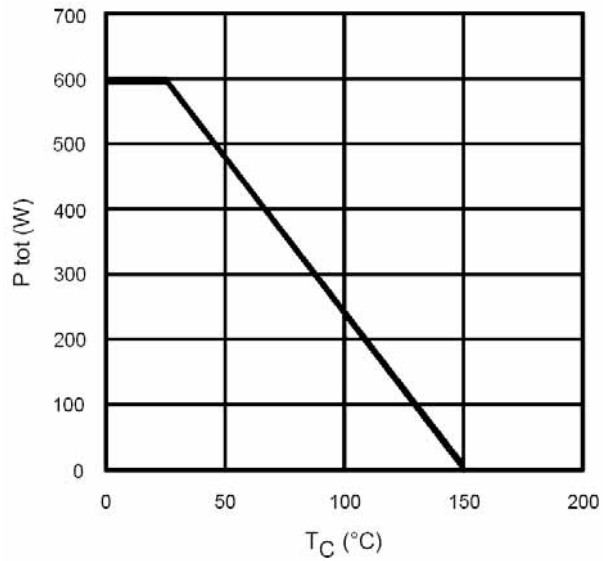
Symbol	Parameters	Min	Typ	Max	Unit	Test conditions
$C_{ies}$	Input capacitance	-	4100	-	pF	$V_{CC} = 30V, V_{GE} = 0V$
$C_{oss}$	Output capacitance	-	395	-		
$C_{res}$	Reverse transfer capacitance	-	160	-		
$t_{d(on)}$	Turn-on delay time	-	72	-	ns	$T_j = 125$ , $V_{CC} = 600V$ $I_C = 75A, V_{GE} = 15V$ $R_G = 4.7\Omega$
$t_r$	Rise time	-	32	-		
$t_{d(off)}$	Turn-off delay time	-	366	-		
$t_f$	Fall time	-	46	-		
$I_{rr}$	Diode Peak Reverse Recovery current	-	55	-	A	$T_j = 125$ , $V_{CC} = 600V$ $I_F = 75A, V_{GE} = 15V$
$t_{rr}$	Diode Reverse Recovery time	-	180	-	ns	$R_G = 4.7\Omega, di/dt=1200A/us$

**Thermal Characteristic Values**

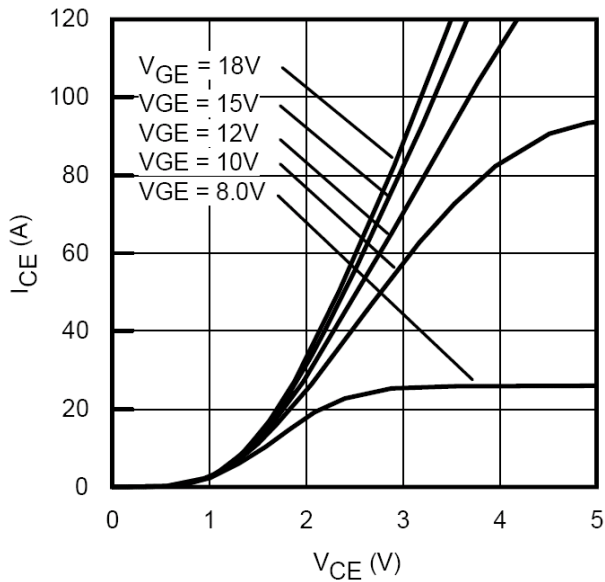
Symbol	Parameters	Min	Typ	Max	Unit
$R_{JC}$	Junction-to-Case (IGBT Part, Per 1/2 Module)	-	-	0.26	/W
$R_{JC}$	Junction-to-Case (Diode Part, Per 1/2 Module)	-	-	0.54	
$R_{CS}$	Case-to-Heat Sink (Conductive grease applied)	-	0.05	-	



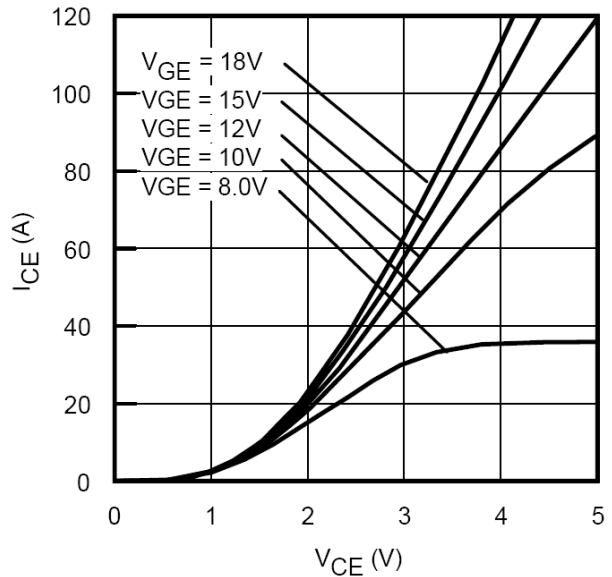
**Fig 1. Maximum DC Collector Current vs. Case Temperature**



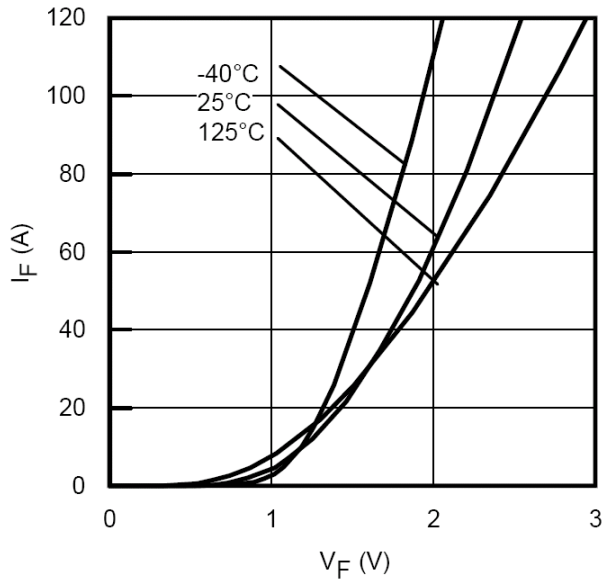
**Fig 2. Power Dissipation vs. Case Temperature**



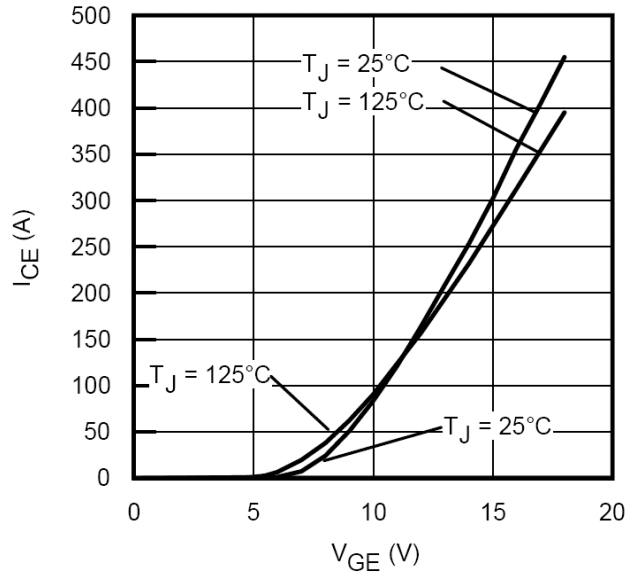
**Fig 3. Typ. IGBT Output Characteristics**  
 $T_J = 25^\circ\text{C}$  ;  $t_p = 80\mu\text{s}$



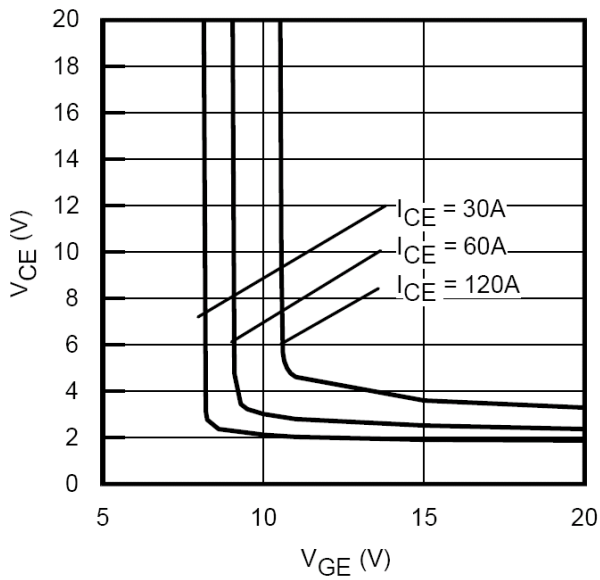
**Fig 4. Typ. IGBT Output Characteristics**  
 $T_J = 125^\circ\text{C}$  ;  $t_p = 80\mu\text{s}$



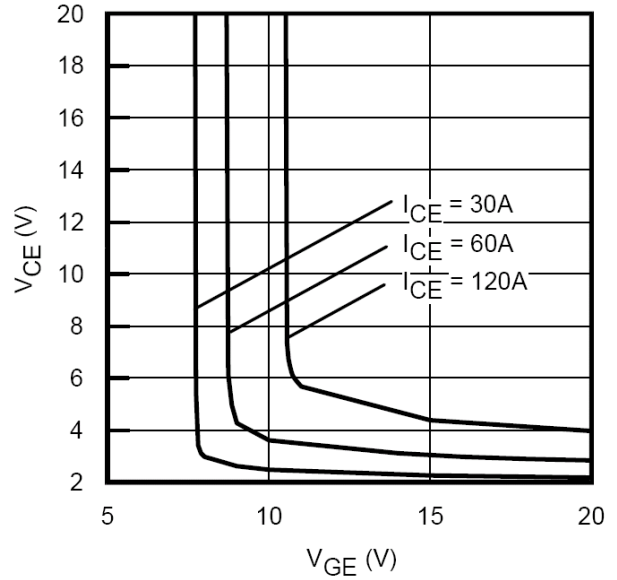
**Fig 5. Typ. Diode Forward Characteristics**  
 $t_p = 80\mu s$



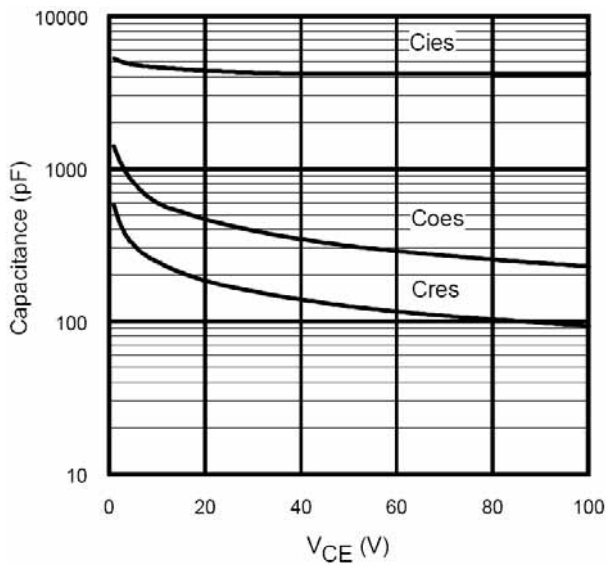
**Fig 6. Typ. Transfer Characteristics**  
 $V_{CE} = 50V; t_p = 10\mu s$



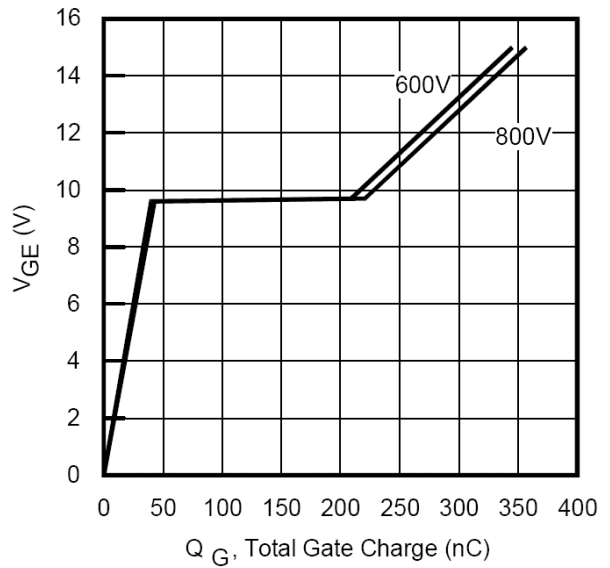
**Fig 7. Typical  $V_{CE}$  vs.  $V_{GE}$**   
 $T_J = 25$



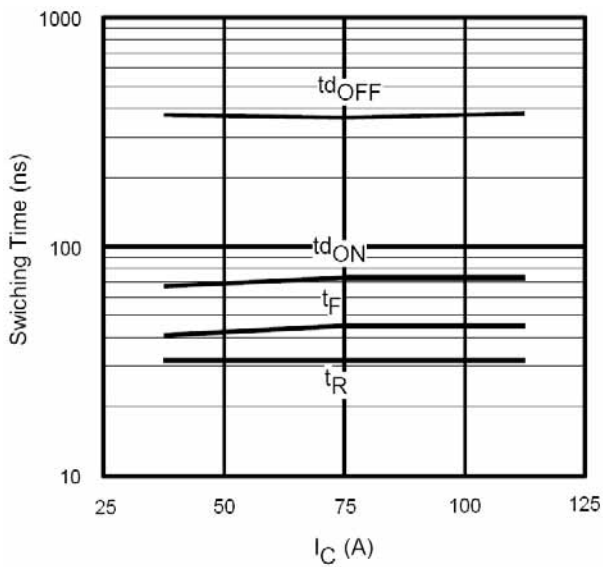
**Fig 8. Typical  $V_{CE}$  vs.  $V_{GE}$**   
 $T_J = 125$



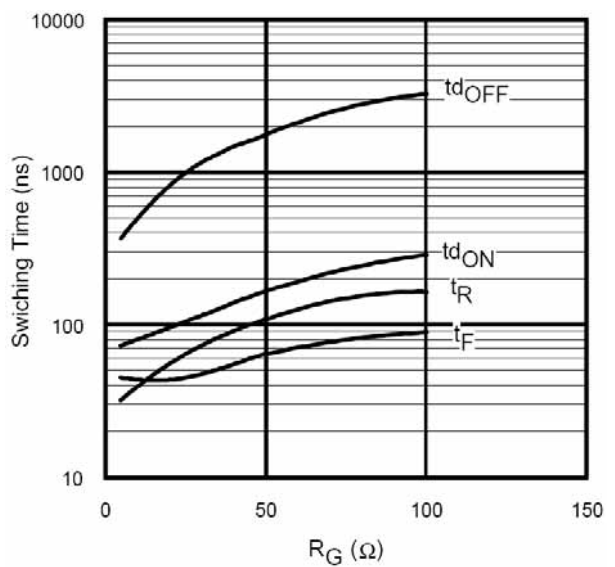
**Fig 9. Typ. Capacitance vs. V<sub>ce</sub>**  
V<sub>GE</sub> = 0V; f = 1Mhz



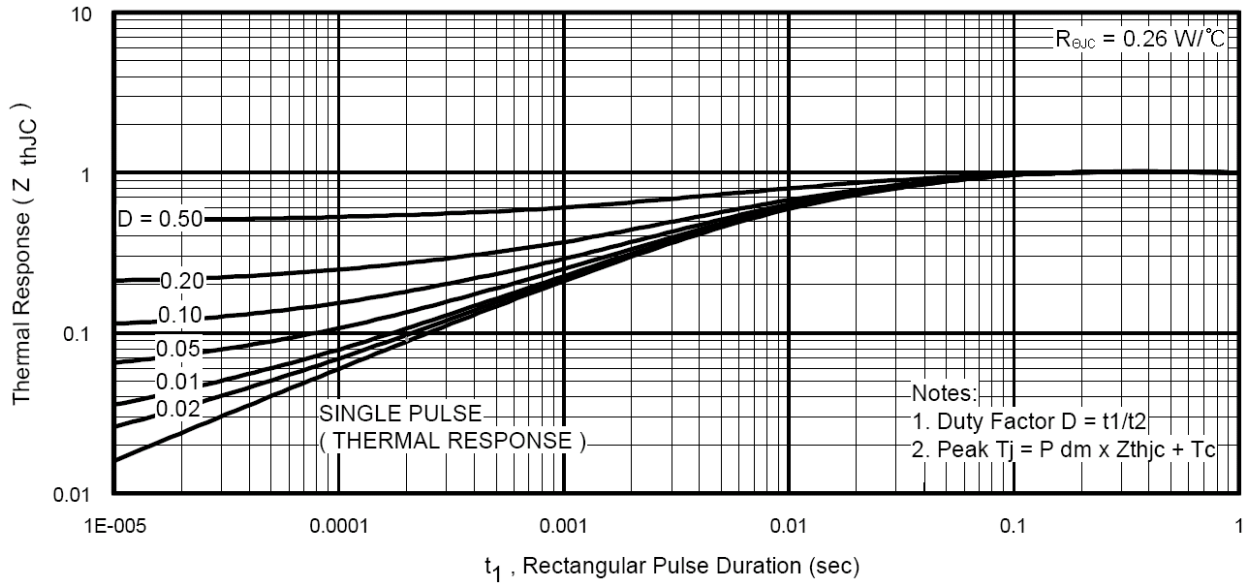
**Fig 10. Typical Gate Charge vs. V<sub>ge</sub>**  
I<sub>CE</sub> = 60A; L = 600μH



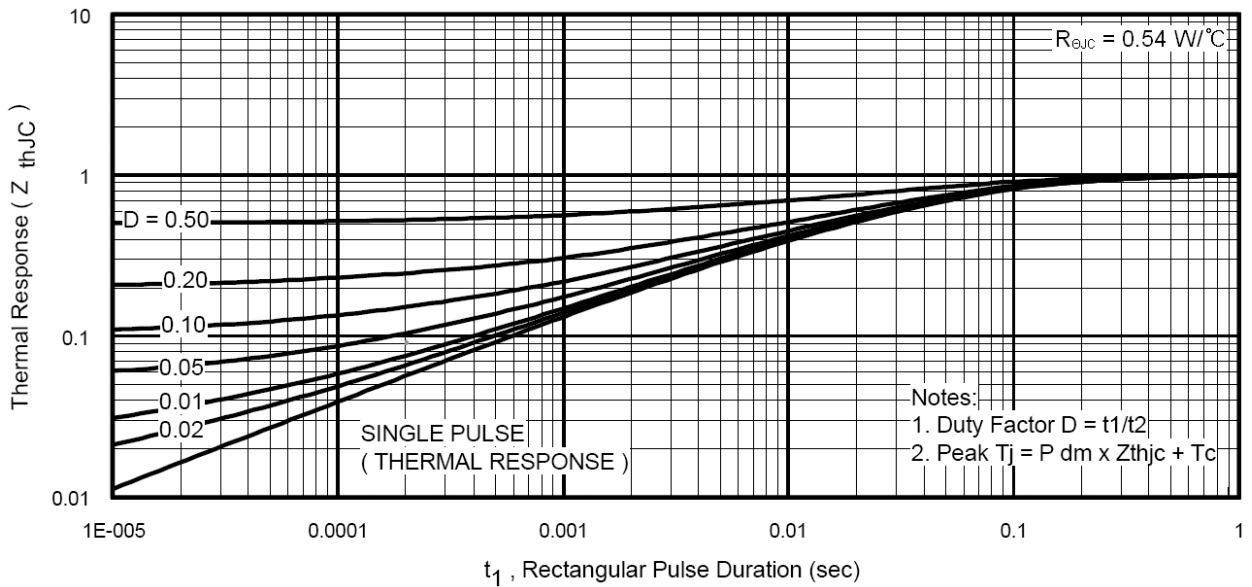
**Fig 11. Typ. Switching Time vs. I<sub>c</sub>**  
T<sub>J</sub> = 125 ; L = 200μH; V<sub>CE</sub> = 600V  
R<sub>G</sub> = 4.7Ω; V<sub>GE</sub> = 15V



**Fig 12. Typ. Switching Time vs. R<sub>g</sub>**  
T<sub>J</sub> = 125 ; L = 200μH; V<sub>CE</sub> = 600V  
I<sub>CE</sub> = 75A; V<sub>GE</sub> = 15V

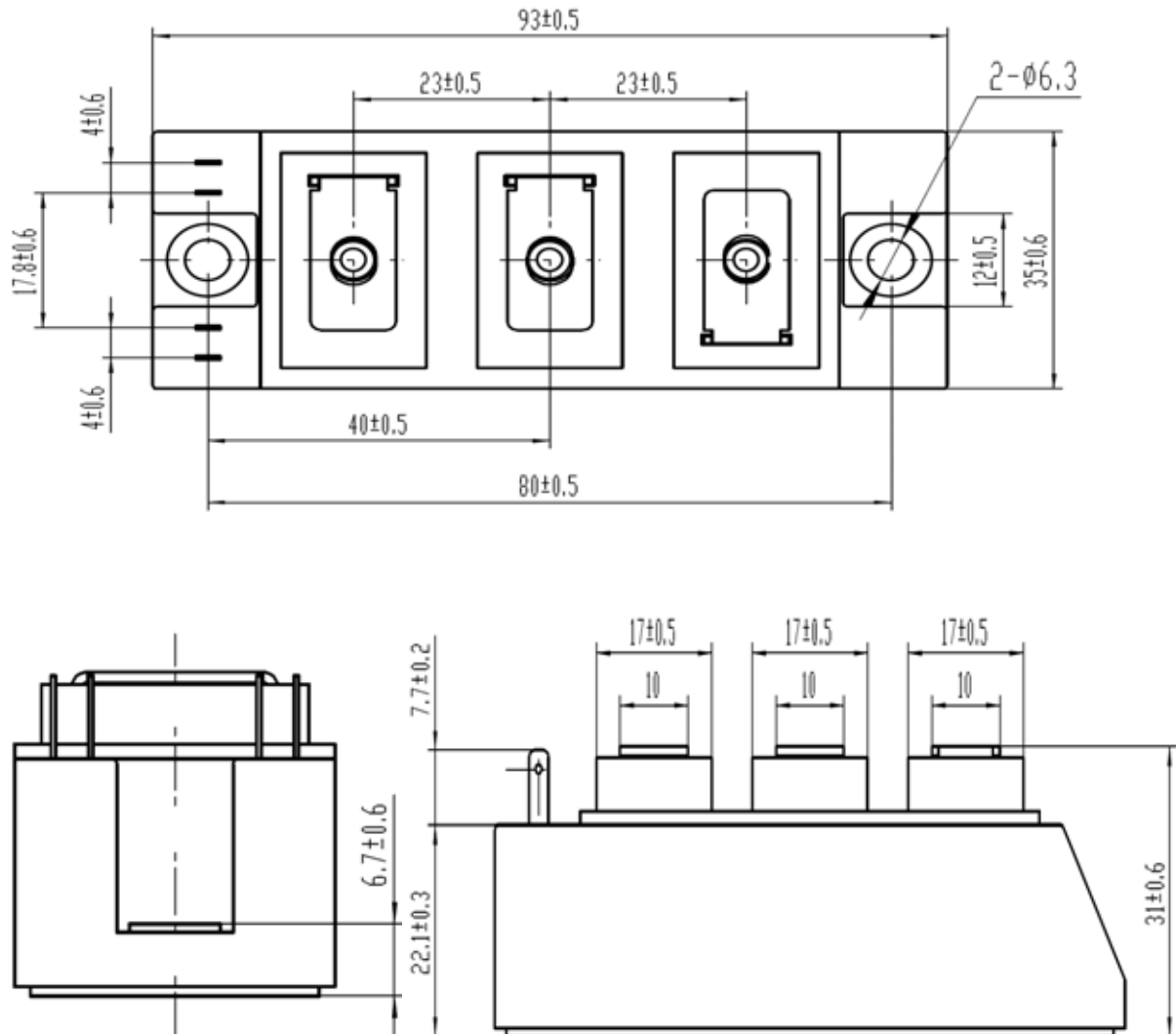


**Fig 13. Normalized Transient Thermal Impedance, Junction-to-Case (IGBT)**



**Fig 14. Normalized Transient Thermal Impedance, Junction-to-Case (DIODE)**

**Package Outline** (dimensions in mm)



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